

Mechanical standardization of semiconductor devices —

Part 6-13: Design guideline of open-top-type sockets for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array (FBGA/FLGA)

The European Standard EN 60191-6-13:2007 has the status of a
British Standard

ICS 01.100.25; 31.080.01

National foreword

This British Standard is the UK implementation of EN 60191-6-13:2007. It is identical to IEC 60191-6-13:2007.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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**Mechanical standardization of semiconductor devices -
Part 6-13: Design guideline of open-top-type sockets
for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array
(FBGA/FLGA)
(IEC 60191-6-13:2007)**

Normalisation mécanique
des dispositifs à semi-conducteurs -
Partie 6-13: Guide de conception
pour les supports sans couvercle
pour les boîtiers FBGA et FLGA

Mechanische Normung
von Halbleiterbauelementen -
Teil 6-13: Konstruktionsleitfaden
für Open-top-Fassungen
für Feinraster-Ball-Grid-Array
und Feinraster-Land-Grid-Array
(FBGA/FLGA)
(IEC 60191-6-13:2007)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
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Foreword

The text of document 47D/681/FDIS, future edition 1 of IEC 60191-6-13, prepared by SC 47D, Mechanical standardization for semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-13 on 2007-09-01.

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- | | | |
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Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-13:2007 was approved by CENELEC as a European Standard without any modification.

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MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-13: Design guideline of open-top-type sockets for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array (FBGA/FLGA)

1 Scope

This part of IEC 60191 gives a design guideline of open-top-type semiconductor sockets for Fine-pitch Ball Grid Array (“FBGA” hereafter) and Fine-pitch Land Grid Array (“FLGA” hereafter). This standard is intended to establish the outline drawings and dimensions of the open-top-type socket out of the test and burn-in sockets applied to FBGA and FLGA.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-2, *Mechanical standardization of semiconductor devices – Part 2: Dimensions*

IEC 60191-6:2004, *Mechanical standardization of semiconductor devices – Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages*

3 Terms and definitions

For the purposes of this document, the terms and definitions of IEC 60191-6 apply.

4 Socket code

4.1 Construction of socket code

A socket code is constructed as follows.

